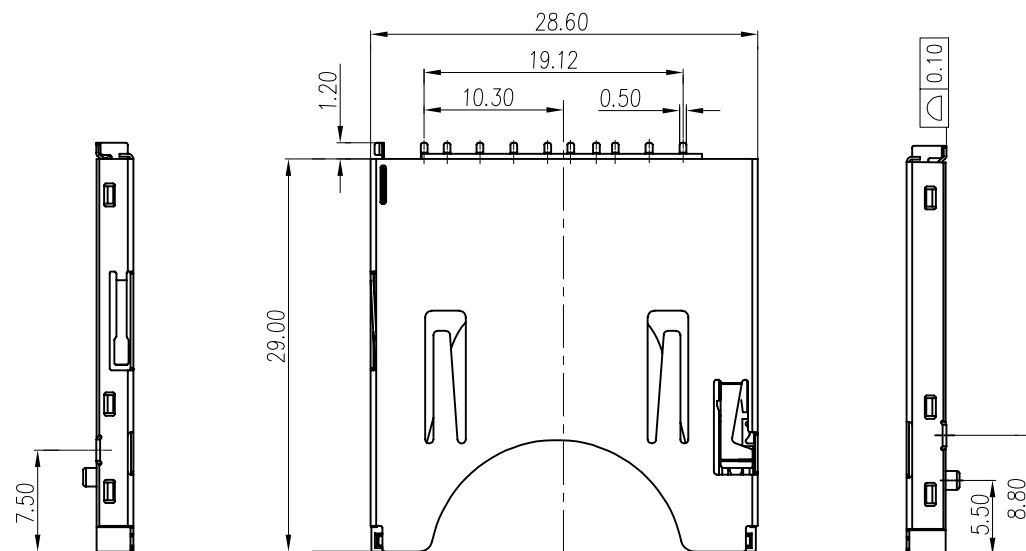


A
B
C
D
E
F

SPECIFICATION

1.MATERIAL:

HOUSING:HIGH TEMPERATURE THERMOPLASTIC

UL 94-0,COLOR:BLACK

CONTACT: COPPER ALLOY

COVER: COPPER ALLOY

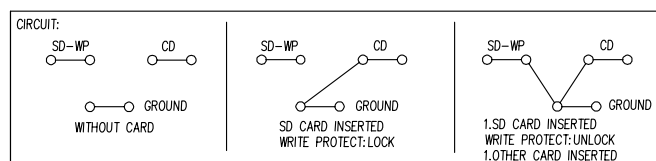
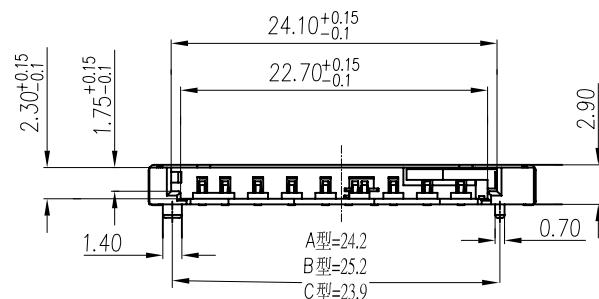
2.PLATING:

UNDERPLATE: NICKEL


CONTACT AREA: GOLD OVER NICKEL

SOLDER AREA: TIN PLATING OVER NICKEL(LEAD FREE).

3.COPLANARITY MUST BE WITHIN 0.10mm

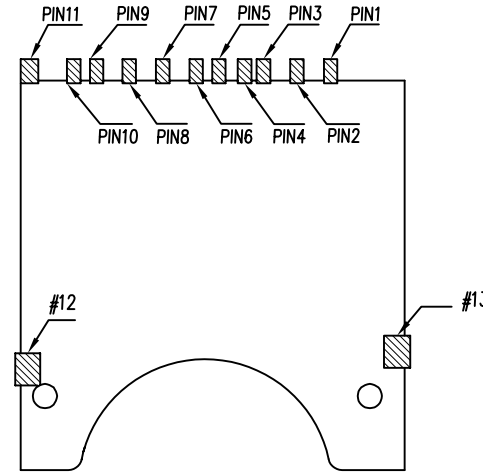
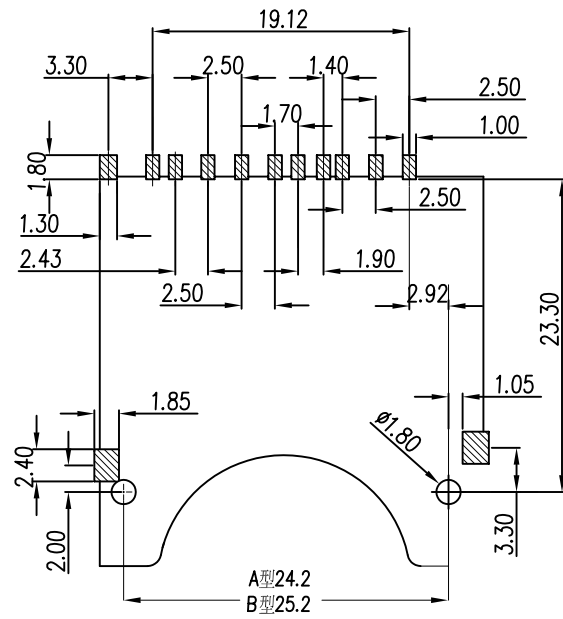


ROHS Compliant

PART NO:		MATERIAL:		 HSI-CHIN ELECTRONICS CO.,LTD		
MODEL NO:		FINSH:				
UNIT: mm	SIZE: A4	COLOR:		PART NAME: SD CARD PUSH CONN		
TOLERANCE UNSPECIFIED		DR: 陳杰 '11/10/26				
.x ±0.30	CHK: Kevin '11/10/26		DWG NO:		0D-S/A-634	REV: A0
.xx ±0.20	APP: Kent '11/10/26		SCALE:		1:1	SHEET: 1 of 2
.xxx ±0.10						
ANG. ±1°						



A
B
C
D
E
F

REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



P.B.T LAYOUT
(TOERANCE ± 0.05)

PIN NO.	Description	PIN NO.	Description
PIN1	SD-DATA2	PIN8	VSS_SD
PIN2	SD-DATA3	PIN9	DAT0_SD
PIN3	SD-CMD	PIN10	DAT1_SD
PIN4	CD	PIN11	WP_SD
PIN5	VSS_SD	#12	VSS-MS
PIN6	VDD_SD	#13	VCC-MS
PIN7	CLK_SD		

PART NO:		MATERIAL:		 HSI-CHIN <small>ELECTRONICS CO.,LTD</small>	
MODEL NO:		FINSH:			
UNIT: mm	SIZE: A4	COLOR:	PART NAME: SD CARD PUSH CONN		
TOLERANCE UNSPECIFIED		DR: 陳杰 '11/10/26			
.x	±0.30	CHK: Kevin '11/10/26	DWG NO:	OD-S/A-634	REV: A0
.xx	±0.20	APP: Kent '11/10/26	SCALE:	1:1	SHEET: 2 of 2
.xxx	±0.10				
ANG.	±1°				

ROHS Compliant

